

ABSTRACT

A method for producing an electronic circuit assembly (e.g., a circuit board) from an etched tri-metal-layer structure which provides air bridge crossovers and specially designed bumps etched from a middle layer of the tri-metal-layer structure. The bumps are formed at particular circuit locations in order to provide interconnects for (1) heavy wirebonding, (2) fine wirebonding, or (3) direct chip attachment; or, to provide lifters for assuring a minimum solder joint standoff height or (5) barriers for retarding solder joint crack propagation.